

Application No.: 10/617,727Docket No.: 2336-193**AMENDMENTS TO THE SPECIFICATION:**

Please amend the paragraph on page 3, beginning at line 1 as follows:

With reference to FIGS. 3a through 3e, there is shown a process of manufacturing such a conventional LED device, comprising forming a lead frame (FIG. 3a), plating (FIG. 3b), pre-molding (FIG. 3c), mounting a chip and wire-bonding (FIG. 3d), and filling epoxy (FIG. 3e). In such a case, the lead frame 31 includes a first pattern part 31a for use in mounting an LED chip thereon, a second pattern part 31b integrated with the first pattern part 31a for use in an electrode, and a third pattern part 31c spaced from the first pattern part 31a so as to be electrically insulated from the first pattern part 31a. On a front surface of the lead frame 31, a metal-plated layer 32 having high adhesion and conductivity is formed to easily perform a wire-bonding process. In FIG. 3c illustrating the pre-molded state, a hexahedron-shaped package 33 having an inner cavity is formed to surround the other portions of the lead frame 31 with the exception of electrode portions of the second and third pattern parts 31b and 31c of the lead frame 31 to be used as external electrodes. An LED chip 34 is mounted on the first pattern part 31a of the lead frame 31 in the package 33, and the LED chip 34 is wire-bonded to each of the second and third pattern parts 31b and 31c in the package 33 to form wire-bonded portions. As shown in FIG. 3e, the package 33 is filled with transparent epoxy 36 to protect the LED chip 34 and the wire-bonded portions.

Abstract:

Please replace the current Abstract with the following replacement/new Abstract.